

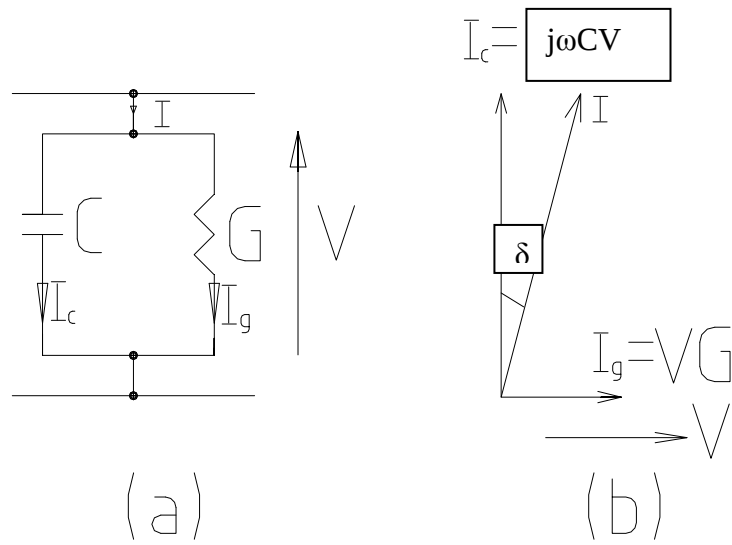


Figure 1 (a) parallel connection of C and G (b) Phasor diagram

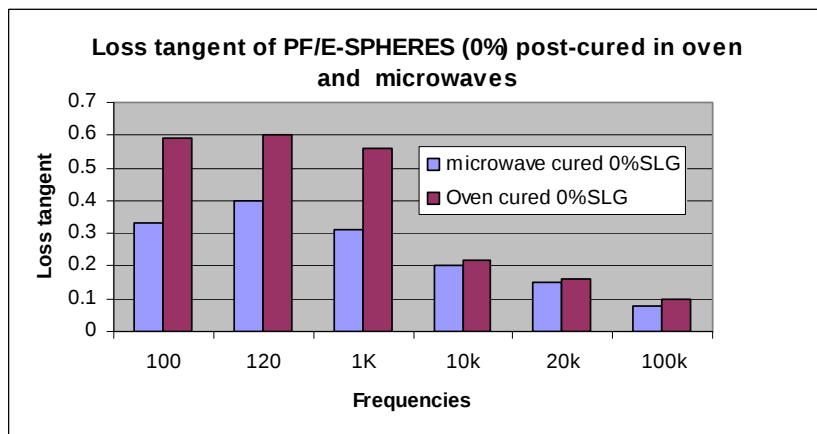


Figure 2: Loss tangent of PF/E-SPHERES (0%) post-cured in oven and microwaves

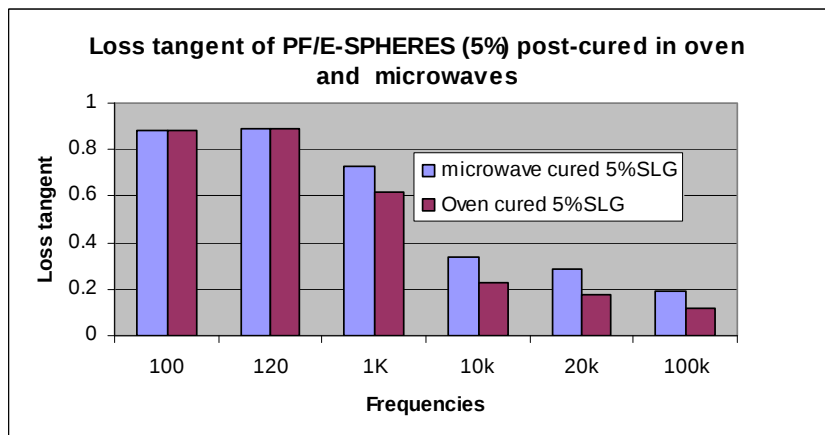


Figure 3: Loss tangent of PF/E-SPHERES (5%) post-cured in oven and microwaves

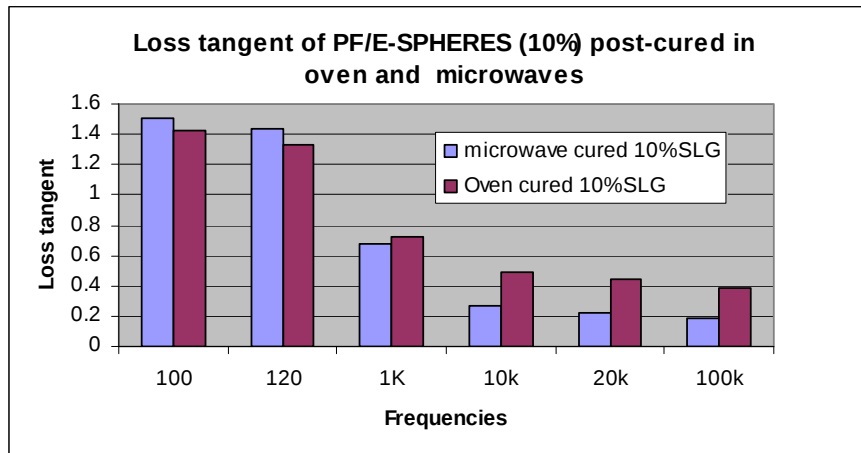


Figure 4: Loss tangent of PF/E-SPHERES (10%) post-cured in oven and microwaves

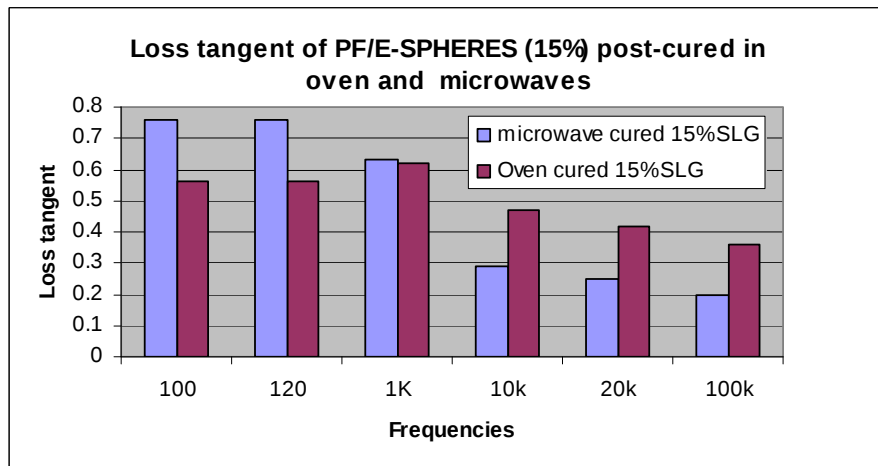


Figure 5: Loss tangent of PF/E-SPHERES (15%) post-cured in oven and microwaves

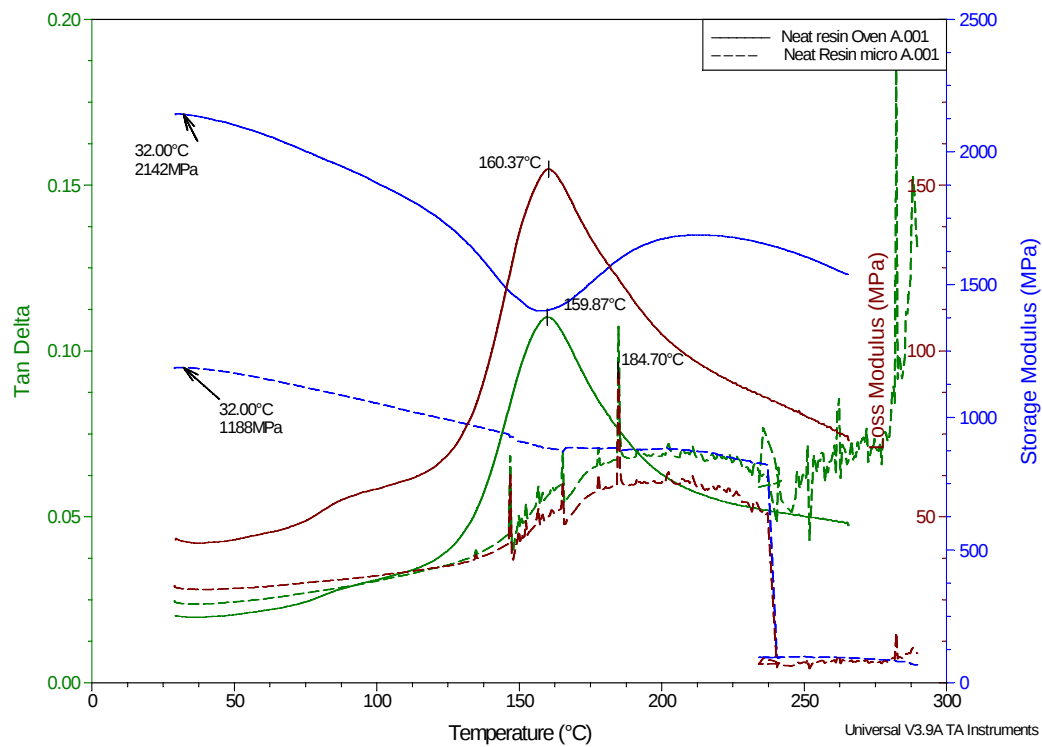


Figure 6: DMA results of neat phenolic resin cured at ambient conditions for 24hours and then post-cured in an oven or microwave facility

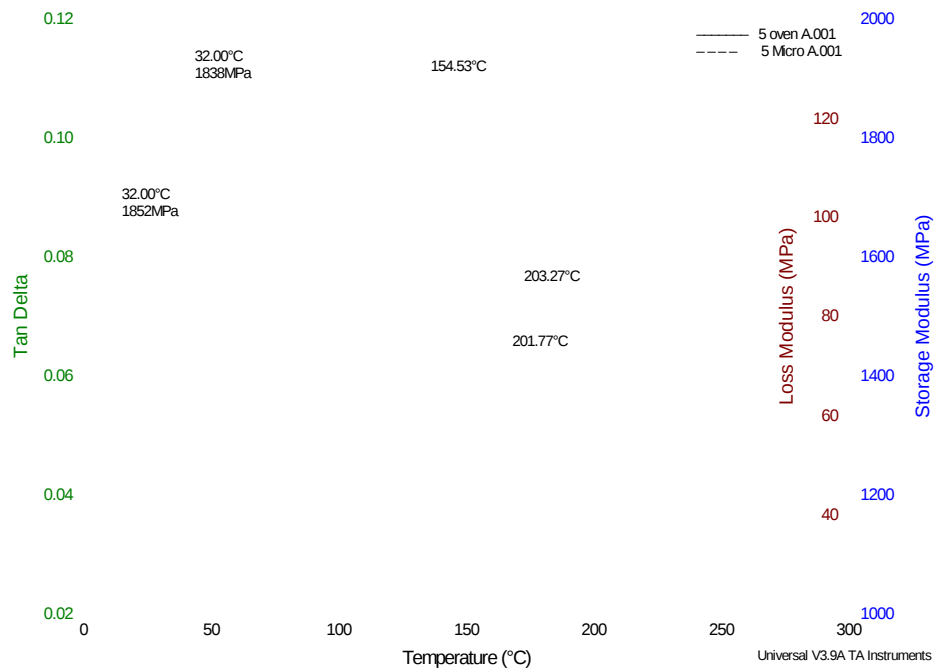


Figure 7: DMA results of 5% SLG reinforced phenolic resin cured at ambient conditions for 24hours and then post-cured in an oven or microwave facility

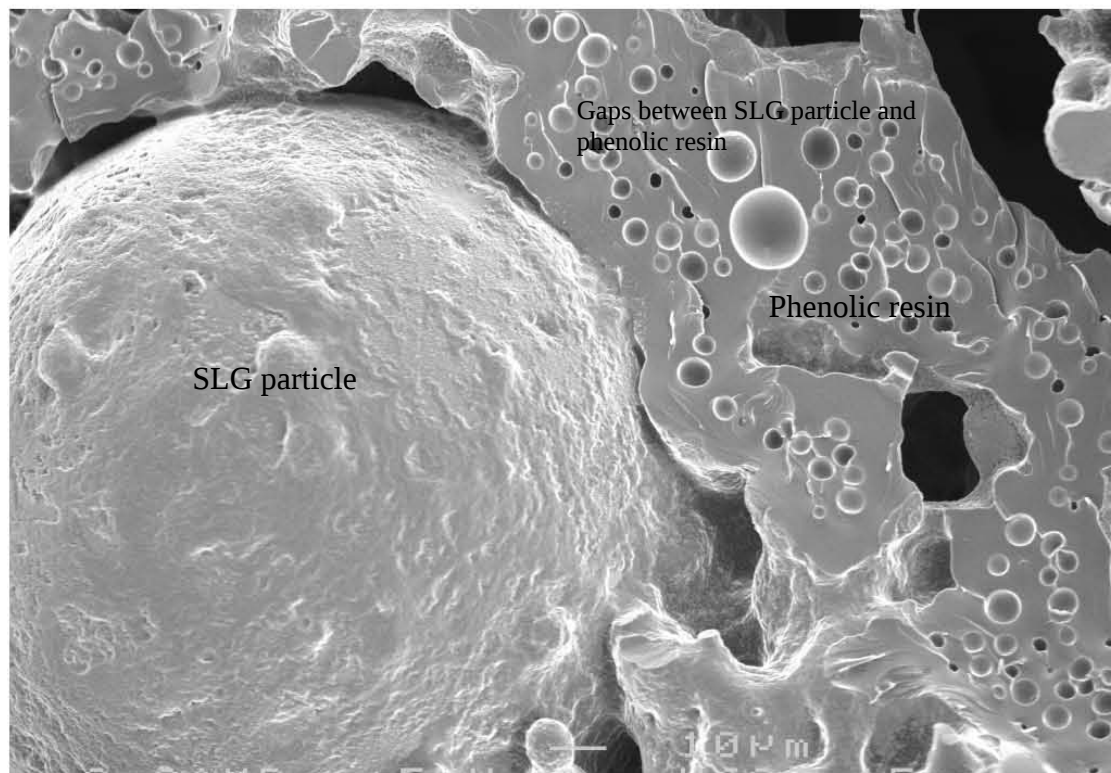


Figure 8: Gaps between SLG particle and phenolic resin

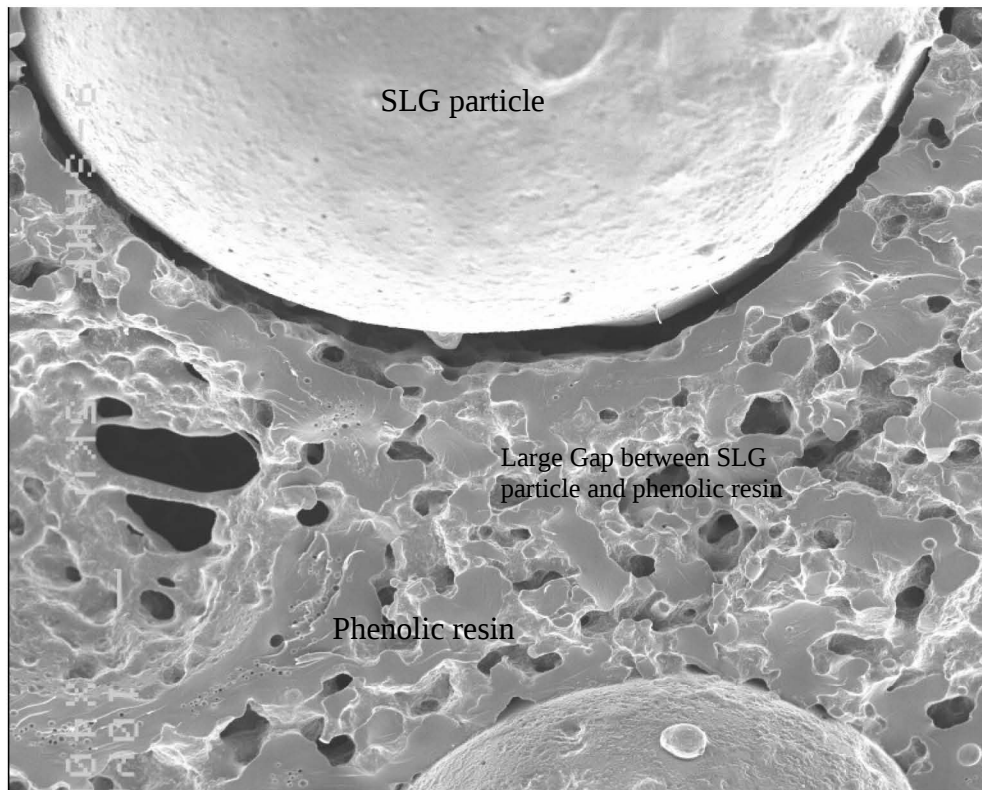


Figure 9: Closer look on more serious gap

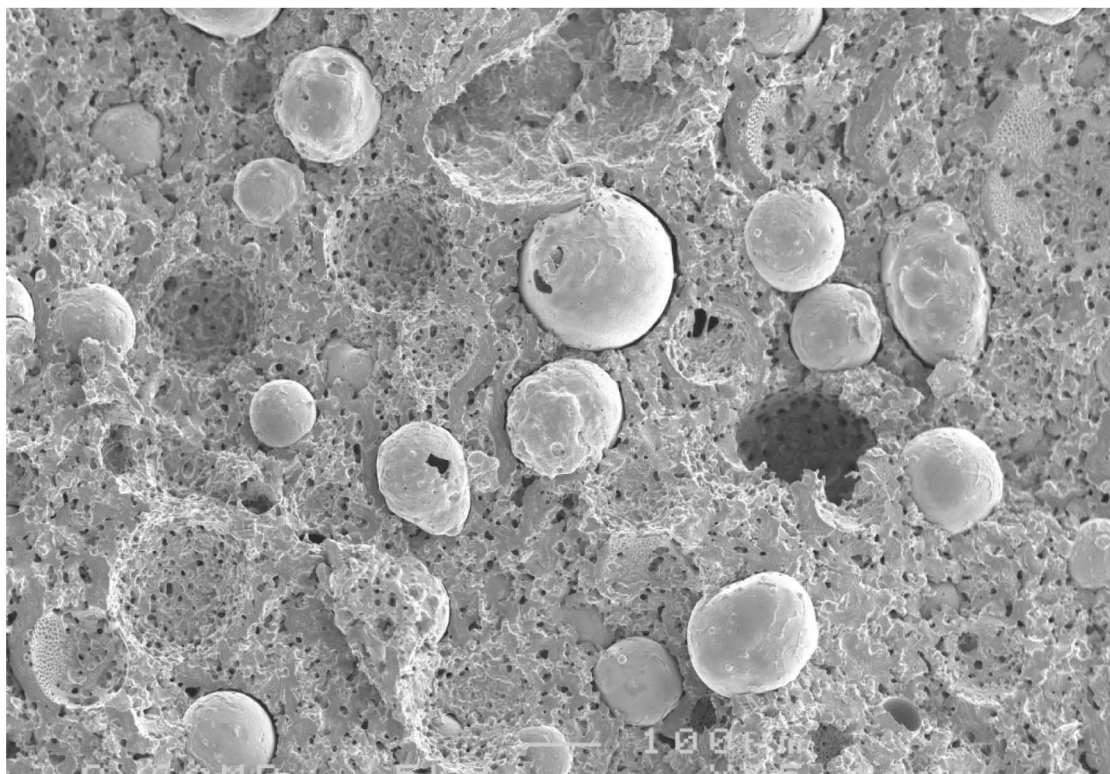


Figure 10: SLG particles (20%) distributed evenly in phenolic resin (80%)

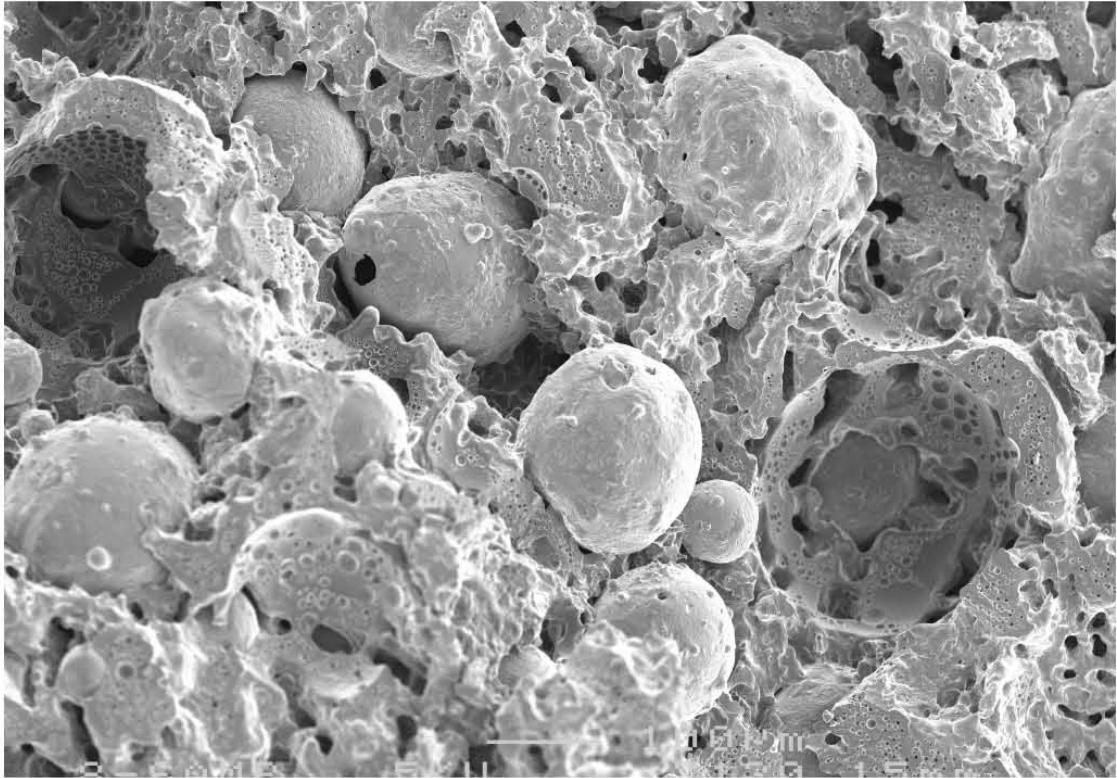


Figure 11: SLG particles (30%) distributed evenly in phenolic resin (70%)